



Material Content Data Sheet



Sales Product Name		BSC080P03LS G		Issued		1. August 2018		
MA#		MA000621168						
Package		PG-TDSON-8-3		Weight*		104.43 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.914	3.75	3.75	37484	37484
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		109	
	non noble metal	iron	7439-89-6	0.038	0.04		362	
	non noble metal	copper	7440-50-8	37.762	36.16	36.21	361598	362069
	noble metal	gold	7440-57-5	1.119	1.07	1.07	10715	10715
wire	noble metal	gold	7440-57-5	1.119	1.07	1.07	10715	10715
encapsulation	organic material	carbon black	1333-86-4	0.091	0.09		870	
	plastics	epoxy resin	-	6.451	6.18		61772	
	inorganic material	silicondioxide	60676-86-0	38.886	37.23	43.50	372369	435011
leadfinish	non noble metal	tin	7440-31-5	1.452	1.39	1.39	13901	13901
plating	noble metal	silver	7440-22-4	0.166	0.16	0.16	1585	1585
solder	non noble metal	tin	7440-31-5	0.064	0.06		614	
	noble metal	silver	7440-22-4	0.080	0.08		767	
	non noble metal	lead	7439-92-1	3.061	2.93	3.07	29314	30695
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		33	
	non noble metal	iron	7439-89-6	0.011	0.01		109	
	non noble metal	copper	7440-50-8	11.320	10.84	10.85	108398	108540
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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